

車載用プリント配線板



R&D

(高周波対応)

High frequency correspondence



https://www.cmk-corp.com

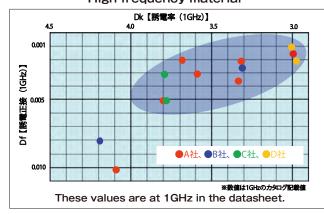
特徴 Features

● 低伝送損失化

誘電率(Low-Dk)/低誘電正接(Low-Df) 基材を採用し アンテナ特性、信号品質の向上を実現します Low7゚ロファイル銅箔も採用し、導体損失も低減します

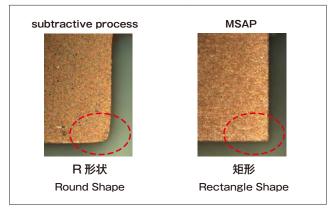
● 新工法の採用 (MSAP: Modified Semi-Additive Process) 回路形成後に要求形状を再現し、アンテナ特性、信号品質の 向上を実現し、Zo、Zdifコントロールに対応します

High frequency material



- Lower Transmission Loss Antenna property and signal quality have been imploved by using low-Dk, low-Df materials.
- New Process (MSAP: Modified Semi-Additive Process) Installed new process have completed circuit pattern requested, and Antenna property and signal quality have been imploved. This process is more suitable for Zo, Zdif control.

Process comparison



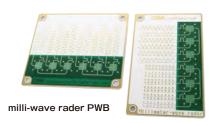
🥡 用途 Application

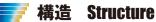
- ADAS・自動運転(ミリ波レーダー、レーザーレーダー)
- 運行支援・通信システム

- ADAS, Autonomous (milli-wave rader, LiDAR)
- Driving assist, Communication system (Automotive) communication, 5G communication)



運行支援・通信システム Driving assist, Communication system





● 異種材との複合構造にも対応

LowDk·Df 基材 LowDk · Df material Hybrid PWB

LowDk·Df 基材 LowDk · Df material

-般 FR-4基材 FR-4 general material

